DECLARATION - USA PATENT APPLICATION

As a below named inventor, I hereby declare that:



My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD AND APPARATUS FOR SUPPORTING A SEMICONDUCTOR WAFER DURING PROCESSING the specification of which:

- (a) is attached hereto; or
- (b) X was filed on January 8, 1999 as Application No. 09 /227,564; or
- (c) X was described and claimed in PCT International Application No. PCT/NL97/00398 filed on July 8, 1998.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56;

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent, design or inventor's certificate or any PCT international application(s) listed below and have also identified below any foreign application(s) for patent, design or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed for the same subject matter having a filing date before that of the application(s) of which priority is claimed:

PRIOR FOREIGN APPLICATION(S)

APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORITY CLAIMED UNDER 37 U.S.C. § 119	
1003538	08/07/96	X YES	NO 🖸
		Q YES	№ 🗖
		Q YES	№ 🗖
		O YES	NO 🗆
		O YES	NO 🗆
			1003538 08/07/96 X YES ☐ YES ☐ YES ☐ YES ☐ YES

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below, and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

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A. Jocket No.NEDER3.001APC

Drive II S A Application(s)						(1	$\sim (\bigcirc) / \square$
Prior U.S.A. Application(s)	i			•			
Application No.:	Filing Date:			Status:			
I hereby declare that made on information and be knowledge that willful false st Section 1001 of Title 18 of the of the application or any pater	tatements and the like a e United States Code a	e true; so mad	and furth e are puni	er that th shable by	ese stat fine or i	ements we imprisonm	re made with ent, or both, ur
					- 		
Full name of sole or first inve	, , ,						
Inventor's signature	AprDay_	11	_Month _	June	_Year _	1999	
Residence (city and country):	Hoge Naarderweg 71	A, NL-	1217 AD	ḤILVERS	UM, Tl	e Netherla	nds
Citizenship: Dutch Post Office Address: Same as	above				÷	-	
Full name of second inventor	: Frank Hunssen					•	
Inventor's signature	Day	. 11	Month_	June	_Year	1999	
Residence (city and country):	Koppellaan 8, NL-372	21 PE I	BILTHOV	EN, The N	letherla	nds	
Citizenship: Dutch	•						
Post Office Address: Same as	above						
Send Correspondence To: KNOBBE, MARTENS, OLS	ON & BEAR, LLP						

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Customer No. 20,995

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